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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I ² C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	85
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx460f512l-80i-pt

PIC32MX3XX/4XX

NOTES:

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number ⁽¹⁾			Pin Type	Buffer Type	Description
	64-pin QFN/TQFP	100-pin TQFP	121-pin XBGA			
CN0	48	74	B11	I	ST	Change notification inputs. Can be software programmed for internal weak pull-ups on all inputs.
CN1	47	73	C10	I	ST	
CN2	16	25	K2	I	ST	
CN3	15	24	K1	I	ST	
CN4	14	23	J2	I	ST	
CN5	13	22	J1	I	ST	
CN6	12	21	H2	I	ST	
CN7	11	20	H1	I	ST	
CN8	4	10	E3	I	ST	
CN9	5	11	F4	I	ST	
CN10	6	12	F2	I	ST	
CN11	8	14	F3	I	ST	
CN12	30	44	L8	I	ST	
CN13	52	81	C8	I	ST	
CN14	53	82	B8	I	ST	
CN15	54	83	D7	I	ST	
CN16	55	84	C7	I	ST	
CN17	31	49	L10	I	ST	
CN18	32	50	L11	I	ST	
CN19	—	80	D8	I	ST	
CN20	—	47	L9	I	ST	
CN21	—	48	K9	I	ST	
IC1	42	68	E9	I	ST	Capture inputs 1-5.
IC2	43	69	E10	I	ST	
IC3	44	70	D11	I	ST	
IC4	45	71	C11	I	ST	
IC5	52	79	A9	I	ST	
OCFA	17	26	L1	I	ST	Output Compare Fault A Input.
OC1	46	72	D9	O	—	Output Compare output 1.
OC2	49	76	A11	O	—	Output Compare output 2
OC3	50	77	A10	O	—	Output Compare output 3.
OC4	51	78	B9	O	—	Output Compare output 4.
OC5	52	81	C8	O	—	Output Compare output 5.
OCFB	30	44	L8	I	ST	Output Compare Fault B Input.
INT0	35,46	55,72	H9,D9	I	ST	External interrupt 0.
INT1	42	18	61	I	ST	External interrupt 1.
INT2	43	19	62	I	ST	External interrupt 2.

Legend: CMOS = CMOS compatible input or output Analog = Analog input P = Power
 ST = Schmitt Trigger input with CMOS levels O = Output I = Input
 TTL = TTL input buffer

Note 1: Pin numbers are provided for reference only. See the “Pin Diagrams” section for device pin availability.

TABLE 4-6: INTERRUPT REGISTERS MAP FOR THE PIC32MX420F032H DEVICE ONLY⁽¹⁾

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
1000	INTCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SS0	0000
		15:0	—	—	—	MVEC	—	—	—	—	—	—	—	—	INT4EP	INT3EP	INT2EP	INT1EP	INT0EP
1010	INTSTAT ⁽²⁾	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
1020	IPTMR	31:16	IPTMR<31:0>																0000
		15:0																	0000
1030	IFS0	31:16	I2C1MIF	I2C1SIF	I2C1BIF	U1TXIF	U1RXIF	U1EIF	—	—	—	OC5IF	IC5IF	T5IF	INT4IF	OC4IF	IC4IF	T4IF	0000
		15:0	INT3IF	OC3IF	IC3IF	T3IF	INT2IF	OC2IF	IC2IF	T2IF	INT1IF	OC1IF	IC1IF	T1IF	INT0IF	CS1IF	CS0IF	CTIF	0000
1040	IFS1	31:16	—	—	—	—	—	—	USBIF	FCEIF	—	—	—	—	—	—	—	—	0000
		15:0	RTCCIF	FSCMIF	I2C2MIF	I2C2SIF	I2C2BIF	U2TXIF	U2RXIF	U2EIF	SPI2RXIF	SPI2TXIF	SPI2EIF	CMP2IF	CMP1IF	PMPIF	AD1IF	CNIF	0000
1060	IEC0	31:16	I2C1MIE	I2C1SIE	I2C1BIE	U1TXIE	U1RXIE	U1EIE	—	—	—	OC5IE	IC5IE	T5IE	INT4IE	OC4IE	IC4IE	T4IE	0000
		15:0	INT3IE	OC3IE	IC3IE	T3IE	INT2IE	OC2IE	IC2IE	T2IE	INT1IE	OC1IE	IC1IE	T1IE	INT0IE	CS1IE	CS0IE	CTIE	0000
1070	IEC1	31:16	—	—	—	—	—	—	USBIE	FCEIE	—	—	—	—	—	—	—	—	0000
		15:0	RTCCIE	FSCMIE	I2C2MIE	I2C2SIE	I2C2BIE	U2TXIE	U2RXIE	U2EIE	SPI2RXIE	SPI2TXIE	SPI2EIE	CMP2IE	CMP1IE	PMPIE	AD1IE	CNIE	0000
1090	IPC0	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
10A0	IPC1	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
10B0	IPC2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
10C0	IPC3	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
10D0	IPC4	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
10E0	IPC5	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
10F0	IPC6	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
1100	IPC7	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
1110	IPC8	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
1140	IPC11	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

- Note 1:** Except where noted, all registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See Section 12.1.1 “CLR, SET and INV Registers” for more information.
- 2:** This register does not have associated CLR, SET, and INV registers.

TABLE 4-9: OUTPUT COMPARE1-5 REGISTERS MAP⁽¹⁾

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3000	OC1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3010	OC1R	31:16	OC1R<31:0>																xxxxx
		15:0																	xxxxx
3020	OC1RS	31:16	OC1RS<31:0>																xxxxx
		15:0																	xxxxx
3200	OC2CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3210	OC2R	31:16	OC2R<31:0>																xxxxx
		15:0																	xxxxx
3220	OC2RS	31:16	OC2RS<31:0>																xxxxx
		15:0																	xxxxx
3400	OC3CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3410	OC3R	31:16	OC3R<31:0>																xxxxx
		15:0																	xxxxx
3420	OC3RS	31:16	OC3RS<31:0>																xxxxx
		15:0																	xxxxx
3600	OC4CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3610	OC4R	31:16	OC4R<31:0>																xxxxx
		15:0																	xxxxx
3620	OC4RS	31:16	OC4RS<31:0>																xxxxx
		15:0																	xxxxx
3800	OC5CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3810	OC5R	31:16	OC5R<31:0>																xxxxx
		15:0																	xxxxx
3820	OC5RS	31:16	OC5RS<31:0>																xxxxx
		15:0																	xxxxx

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See Section 12.1.1 "CLR, SET and INV Registers" for more information.

TABLE 4-10: I2C1-2 REGISTERS MAP⁽¹⁾

Virtual Address (BF80_#)	Register Name	Bit Range	Bits															All Resets	
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1		16/0
5000	I2C1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	SCLREL	STRICT	A10M	DISSLW	SMEN	GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	1000
5010	I2C1STAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ACKSTAT	TRSTAT	—	—	—	—	BCL	GCSTAT	ADD10	IWCOL	I2COV	D/A	P	S	R/W	RBF	TBF
5020	I2C1ADD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
5030	I2C1MSK	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
5040	I2C1BRG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
5050	I2C1TRN	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
5260	I2C1RCV	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
5200	I2C2CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	SCLREL	STRICT	A10M	DISSLW	SMEN	GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	1000
5210	I2C2STAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ACKSTAT	TRSTAT	—	—	—	—	BCL	GCSTAT	ADD10	IWCOL	I2COV	D/A	P	S	R/W	RBF	TBF
5220	I2C2ADD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
5230	I2C2MSK	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
5240	I2C2BRG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
5250	I2C2TRN	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
5260	I2C2RCV	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table except I2CxRCV have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

TABLE 4-19: FLASH CONTROLLER REGISTERS MAP

Virtual Address (BF80_#)	Register Name	Bit Range	Bits														All Resets	
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2		17/1
F400	NVMCON ⁽¹⁾	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	WR	WREN	WRERR	LVDERR	LVDSTAT	—	—	—	—	—	—	—	NVMOP<3:0>			0000
F410	NVMKEY	31:16	NVMKEY<31:0>														0000	
		15:0															0000	
F420	NVMADDR ⁽¹⁾	31:16	NVMADDR<31:0>														0000	
		15:0															0000	
F430	NVMDATA	31:16	NVMDATA<31:0>														0000	
		15:0															0000	
F440	NVMSRC ADDR	31:16	NVMSRCADDR<31:0>														0000	
		15:0															0000	

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See Section 12.1.1 "CLR, SET and INV Registers" for more information.

TABLE 4-20: SYSTEM CONTROL REGISTERS MAP^(1,2)

Virtual Address (BF80_#)	Register Name	Bit Range	Bits														All Resets		
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2		17/1	16/0
F000	OSCCON	31:16	—	—	PLLODIV<2:0>			FRCDIV<2:0>			—	SOSCRDY	PBDIV<1:0>			PLLMULT<2:0>			0000
		15:0	—	COSC<2:0>			—	NOSC<2:0>			CLKLOCK	ULOCK	SLOCK	SLPEN	CF	UFRGEN	SOSCEN	OSWEN	0000
F010	OSCTUN	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000	
		15:0	—	—	—	—	—	—	—	—	—	TUN<5:0>					0000		
0000	WDTCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000	
		15:0	ON	—	—	—	—	—	—	—	SWDTPS<4:0>					—	WDTCLR	0000	
F600	RCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000	
		15:0	—	—	—	—	—	—	CMR	VREGS	EXTR	SWR	—	WDTO	SLEEP	IDLE	BOR	POR	0000
F610	RSWRST	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000	
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SWRST	0000
F230	SYSKEY ⁽³⁾	31:16	SYSKEY<31:0>														0000		
		15:0															0000		

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: Except where noted, all registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See Section 12.1.1 "CLR, SET and INV Registers" for more information.

Note 2: Reset values are dependent on the DEVCFGx Configuration bits and the type of reset.

Note 3: This register does not have associated CLR, SET, and INV registers.

5.0 FLASH PROGRAM MEMORY

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 5. “Flash Program Memory”** (DS61121) of the *“PIC32 Family Reference Manual”*, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

RTSP is performed by software executing from either Flash or RAM memory. EJTAG is performed using the EJTAG port of the device and a EJTAG capable programmer. ICSP is performed using a serial data connection to the device and allows much faster programming times than RTSP. RTSP techniques are described in this chapter. The ICSP and EJTAG methods are described in the *“PIC32MX Flash Programming Specification”* (DS61145), which can be downloaded from the Microchip web site.

Note: Flash LVD Delay (LVDstartup) must be taken into account between setting up and executing any Flash command operation. See Example 5-1 for a code example to set up and execute a Flash command operation.

PIC32MX3XX/4XX devices contain an internal program Flash memory for executing user code. There are three methods by which the user can program this memory:

- Run-Time Self Programming (RTSP)
- In-Circuit Serial Programming™ (ICSP™)
- EJTAG Programming

EXAMPLE 5-1:

```
NVMCON = 0x4004;           // Enable and configure for erase operation
Wait(delay);              // Delay for 6 µs for LVDstartup

NVMKEY = 0xAA996655;
NVMKEY = 0x556699AA;
NVMCONSET = 0x8000;       // Initiate operation

while(NVMCONbits.WR==1); // Wait for current operation to complete
```

PIC32MX3XX/4XX

NOTES:

PIC32MX3XX/4XX

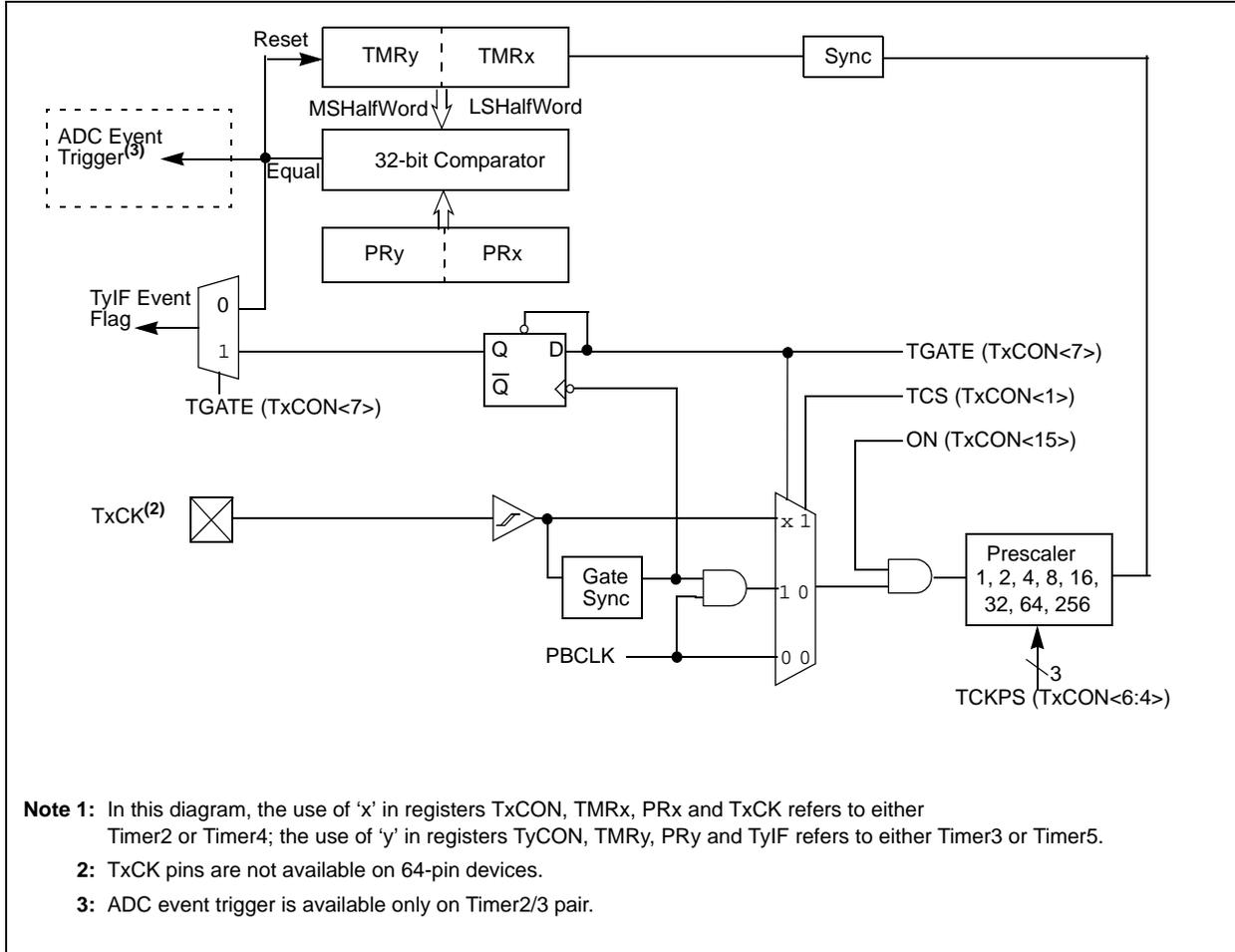
NOTES:

PIC32MX3XX/4XX

NOTES:

PIC32MX3XX/4XX

FIGURE 14-2: TIMER2/3, 4/5 BLOCK DIAGRAM (32-BIT)



24.0 COMPARATOR VOLTAGE REFERENCE (CVREF)

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. Refer to **Section 20. “Comparator Voltage Reference (CVREF)”** (DS61109) of the “PIC32 Family Reference Manual”, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

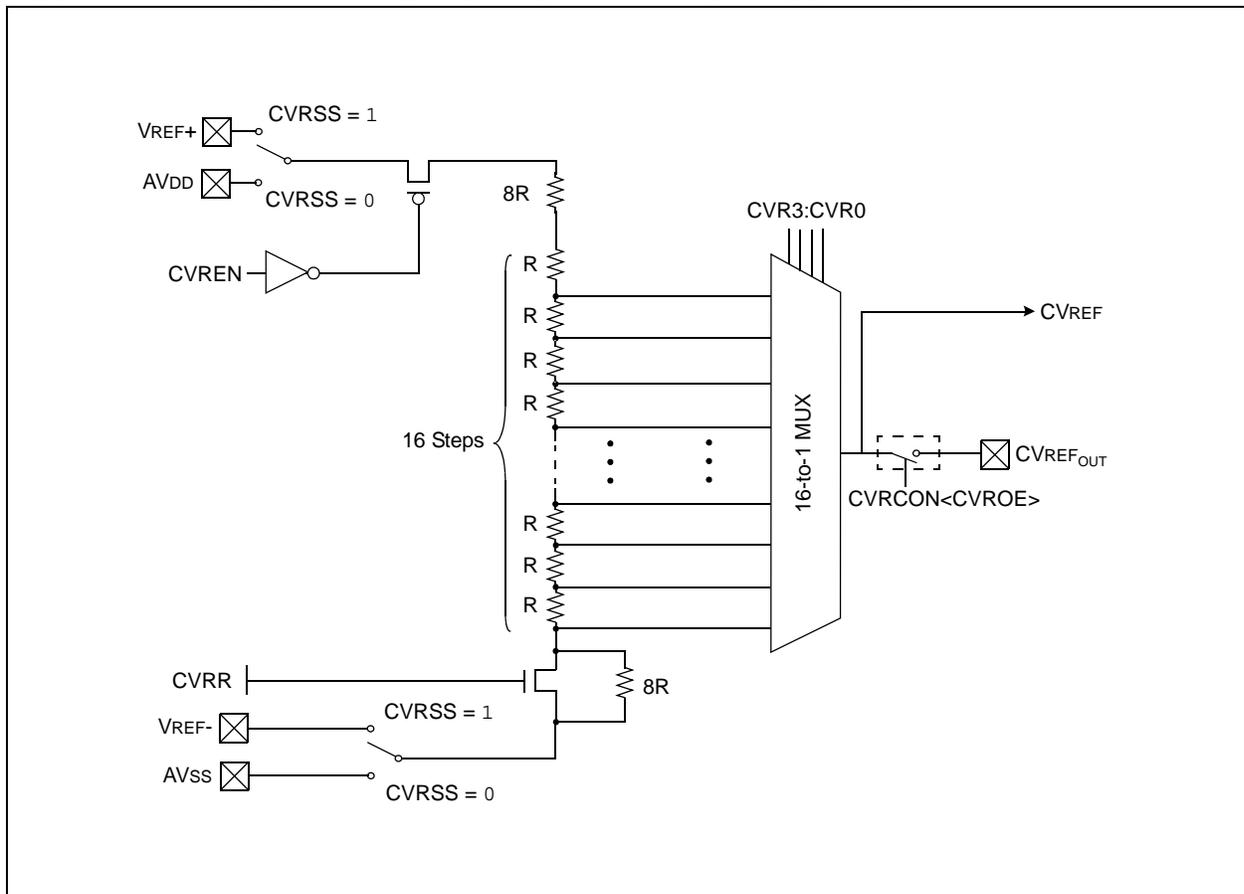
The CVREF is a 16-tap, resistor ladder network that provides a selectable reference voltage. Although its primary purpose is to provide a reference for the analog comparators, it also may be used independently of them.

A block diagram of the module is illustrated in Figure 24-1. The resistor ladder is segmented to provide two ranges of voltage reference values and has a power-down function to conserve power when the reference is not being used. The module’s supply reference can be provided from either device VDD/VSS or an external voltage reference. The CVREF output is available for the comparators and typically available for pin output.

The comparator voltage reference has the following features:

- High and low range selection
- Sixteen output levels available for each range
- Internally connected to comparators to conserve device pins
- Output can be connected to a pin

FIGURE 24-1: COMPARATOR VOLTAGE REFERENCE BLOCK DIAGRAM



PIC32MX3XX/4XX

NOTES:

28.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers and dsPIC® digital signal controllers are supported with a full range of software and hardware development tools:

- Integrated Development Environment
 - MPLAB® IDE Software
- Compilers/Assemblers/Linkers
 - MPLAB C Compiler for Various Device Families
 - HI-TECH C for Various Device Families
 - MPASM™ Assembler
 - MPLINK™ Object Linker/
MPLIB™ Object Librarian
 - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
 - MPLAB SIM Software Simulator
- Emulators
 - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers
 - MPLAB ICD 3
 - PICKit™ 3 Debug Express
- Device Programmers
 - PICKit™ 2 Programmer
 - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits, and Starter Kits

28.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8/16/32-bit microcontroller market. The MPLAB IDE is a Windows® operating system-based application that contains:

- A single graphical interface to all debugging tools
 - Simulator
 - Programmer (sold separately)
 - In-Circuit Emulator (sold separately)
 - In-Circuit Debugger (sold separately)
- A full-featured editor with color-coded context
- A multiple project manager
- Customizable data windows with direct edit of contents
- High-level source code debugging
- Mouse over variable inspection
- Drag and drop variables from source to watch windows
- Extensive on-line help
- Integration of select third party tools, such as IAR C Compilers

The MPLAB IDE allows you to:

- Edit your source files (either C or assembly)
- One-touch compile or assemble, and download to emulator and simulator tools (automatically updates all project information)
- Debug using:
 - Source files (C or assembly)
 - Mixed C and assembly
 - Machine code

MPLAB IDE supports multiple debugging tools in a single development paradigm, from the cost-effective simulators, through low-cost in-circuit debuggers, to full-featured emulators. This eliminates the learning curve when upgrading to tools with increased flexibility and power.

PIC32MX3XX/4XX

29.1 DC Characteristics

TABLE 29-1: OPERATING MIPS VS. VOLTAGE

Characteristic	VDD Range (in Volts)	Temp. Range (in °C)	Max. Frequency
			PIC32MX3XX/4XX
DC5	2.3V-3.6V	-40°C to +85°C	80 MHz (Note 1)
DC5b	2.3V-3.6V	-40°C to +105°C	80 MHz (Note 1)

Note 1: 40 MHz maximum for PIC32MX320F032H and PIC32MX420F032H devices.

TABLE 29-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min.	Typical	Max.	Unit
Industrial Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+125	°C
Operating Ambient Temperature Range	TA	-40	—	+85	°C
V-Temp Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+140	°C
Operating Ambient Temperature Range	TA	-40	—	+105	°C
Power Dissipation: Internal Chip Power Dissipation: PINT = VDD x (IDD – S IOH) I/O Pin Power Dissipation: I/O = S ((VDD – VOH) x IOH) + S (VOL x IOL)	PD	PINT + PI/O			W
Maximum Allowed Power Dissipation	PDMAX	(TJ – TA)/θJA			W

TABLE 29-3: THERMAL PACKAGING CHARACTERISTICS

Characteristics	Symbol	Typical	Max.	Unit	Notes
Package Thermal Resistance, 121-Pin XBGA (10x10x1.1 mm)	θJA	40	—	°C/W	1
Package Thermal Resistance, 100-Pin TQFP (12x12x1 mm)	θJA	43	—	°C/W	1
Package Thermal Resistance, 64-Pin TQFP (10x10x1 mm)	θJA	47	—	°C/W	1
Package Thermal Resistance, 64-Pin QFN (9x9x0.9 mm)	θJA	28	—	°C/W	1

Note 1: Junction to ambient thermal resistance, Theta-JA (θJA) numbers are achieved by package simulations.

TABLE 29-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS		Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp					
Param. No.	Symbol	Characteristics	Min.	Typical	Max.	Units	Conditions
Operating Voltage							
DC10	VDD	Supply Voltage	2.3	—	3.6	V	—
DC12	VDR	RAM Data Retention Voltage (Note 1)	1.75	—	—	V	—
DC16	VPOR	VDD Start Voltage to Ensure Internal Power-on Reset Signal	1.75	—	1.95	V	—
DC17	SVDD	VDD Rise Rate to Ensure Internal Power-on Reset Signal	0.05	—	—	V/ms	—

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

29.2 AC Characteristics and Timing Parameters

The information contained in this section defines PIC32MX3XX/4XX AC characteristics and timing parameters.

FIGURE 29-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

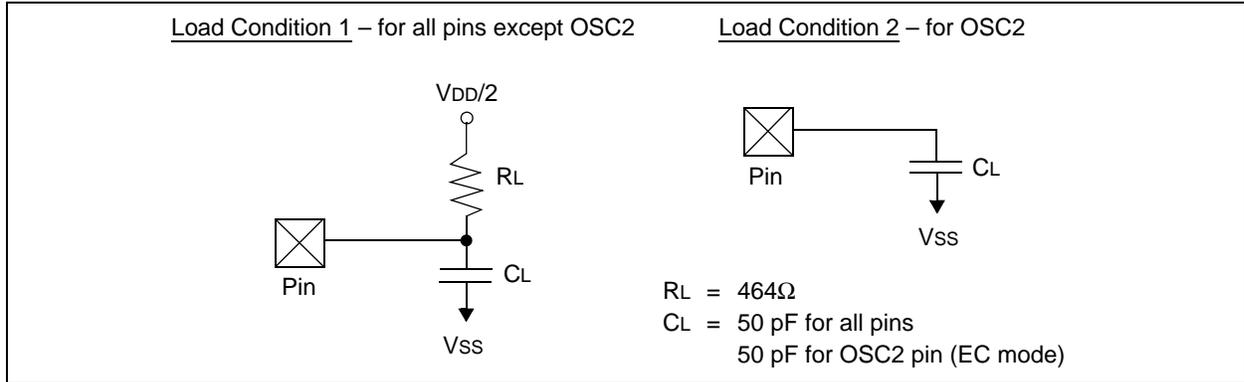
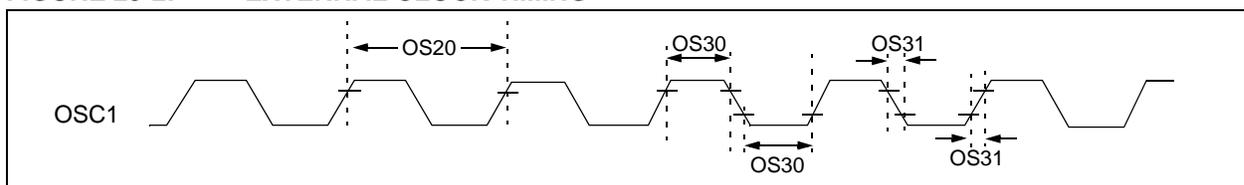


TABLE 29-16: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$ for Industrial $-40^\circ\text{C} \leq T_A \leq +105^\circ\text{C}$ for V-Temp				
Param. No.	Symbol	Characteristics	Min.	Typical ⁽¹⁾	Max.	Units	Conditions
DO56	CIO	All I/O pins and OSC2	—	—	50	pF	EC mode
DO58	CB	SCLx, SDAx	—	—	400	pF	In I ² C™ mode

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

FIGURE 29-2: EXTERNAL CLOCK TIMING



PIC32MX3XX/4XX

TABLE 29-17: EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	Symbol	Characteristics	Min.	Typical ⁽¹⁾	Max.	Units	Conditions
OS10	Fosc	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes)	DC 4	— —	50 ⁽³⁾ 50 ⁽⁵⁾	MHz MHz	EC (Note 5) ECPLL (Note 4)
OS11		Oscillator Crystal Frequency	3	—	10	MHz	XT (Note 5)
OS12			4	—	10	MHz	XTPLL (Notes 4, 5)
OS13			10	—	25	MHz	HS (Note 5)
OS14			10	—	25	MHz	HSPLL (Notes 4, 5)
OS15			32	32.768	100	kHz	Sosc (Note 5)
OS20	Tosc	Tosc = 1/Fosc = Tcy ⁽²⁾	—	—	—	—	See parameter OS10 for Fosc value
OS30	TosL, TosH	External Clock In (OSC1) High or Low Time	0.45 x Tosc	—	—	ns	EC (Note 5)
OS31	TosR, TosF	External Clock In (OSC1) Rise or Fall Time	—	—	0.05 x Tosc	ns	EC (Note 5)
OS40	TOST	Oscillator Start-up Timer Period (Only applies to HS, HSPLL, XT, XTPLL and Sosc Clock Oscillator modes)	—	1024	—	Tosc	(Note 5)
OS41	TFSCM	Primary Clock Fail Safe Time-out Period	—	2	—	ms	(Note 5)
OS42	GM	External Oscillator Transconductance	—	12	—	mA/V	VDD = 3.3V TA = +25°C (Note 5)

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are characterized but are not tested.

- 2:** Instruction cycle period (Tcy) equals the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKI pin.
- 3:** 40 MHz maximum for PIC32MX320F032H and PIC32MX420F032H devices.
- 4:** PLL input requirements: 4 MHz ≤F_{PLLIN} ≤5 MHz (use PLL prescaler to reduce Fosc). This parameter is characterized, but tested at 10 MHz only at manufacturing.
- 5:** This parameter is characterized, but not tested in manufacturing.

PIC32MX3XX/4XX

FIGURE 29-9: OC/PWM MODULE TIMING CHARACTERISTICS

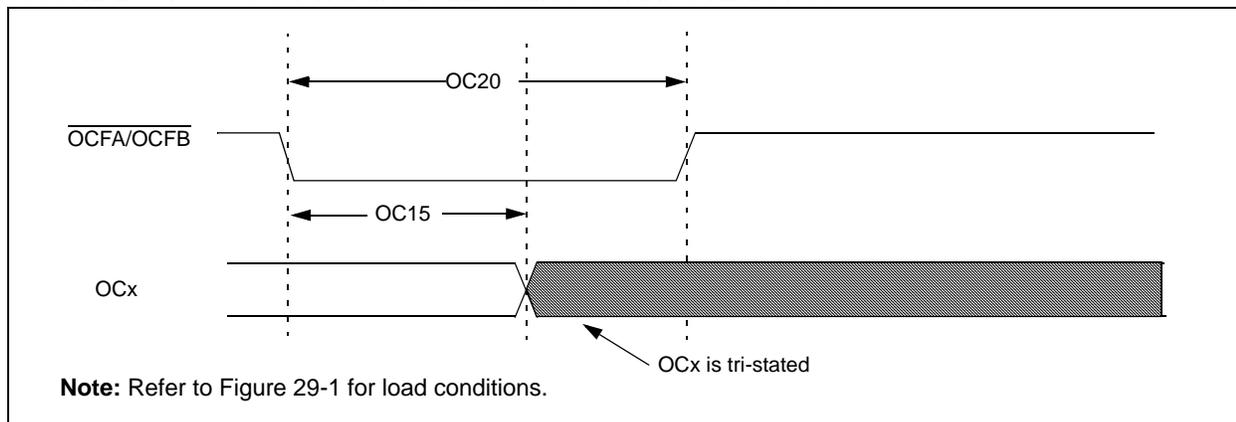


TABLE 29-27: SIMPLE OC/PWM MODE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param No.	Symbol	Characteristics ⁽¹⁾	Min	Typical ⁽²⁾	Max	Units	Conditions
OC15	TFD	Fault Input to PWM I/O Change	—	—	25	ns	—
OC20	TFLT	Fault Input Pulse Width	50	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

Note 2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

FIGURE 29-12: SPIx MODULE SLAVE MODE (CKE = 0) TIMING CHARACTERISTICS

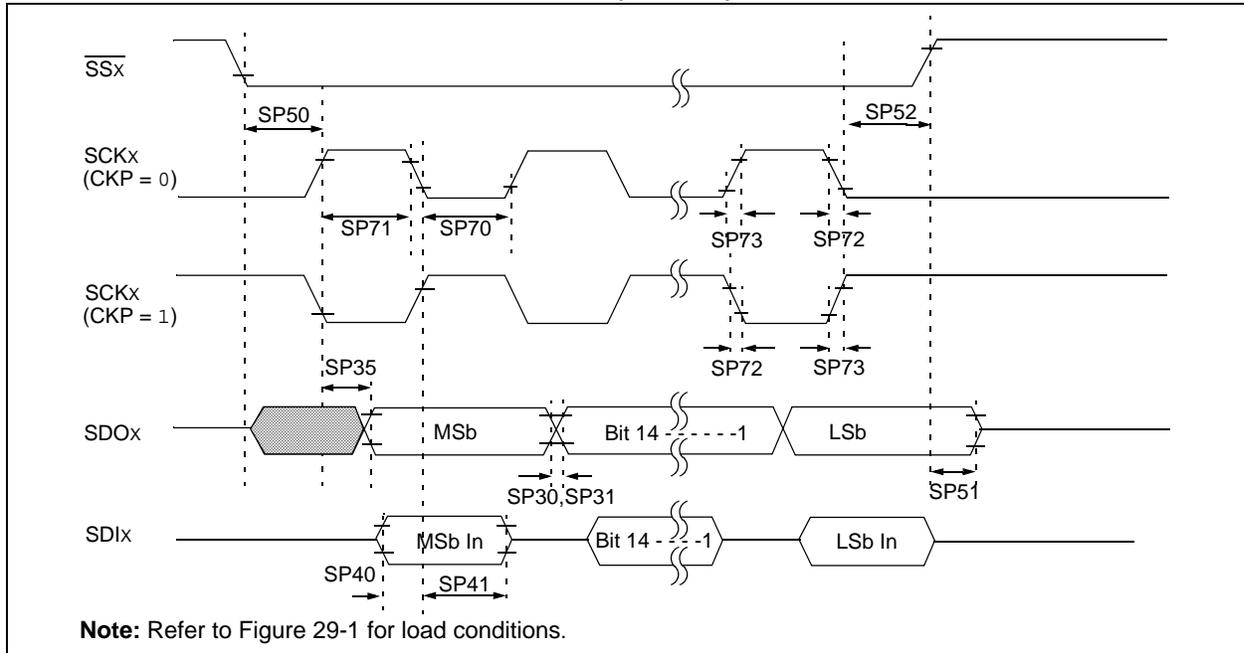


TABLE 29-30: SPIx MODULE SLAVE MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp				
Param. No.	Symbol	Characteristics ⁽¹⁾	Min.	Typical ⁽²⁾	Max.	Units	Conditions
SP70	TsCL	SCKx Input Low Time ⁽³⁾	Tsck/2	—	—	ns	—
SP71	TsCH	SCKx Input High Time ⁽³⁾	Tsck/2	—	—	ns	—
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See parameter DO32
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See parameter DO31
SP30	TdoF	SDOx Data Output Fall Time ⁽⁴⁾	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time ⁽⁴⁾	—	—	—	ns	See parameter DO31
SP35	Tsch2doV, Tscl2doV	SDOx Data Output Valid after SCKx Edge	—	—	15	ns	VDD > 2.7V
			—	—	20	ns	VDD < 2.7V
SP40	Tdiv2sch, Tdiv2scl	Setup Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP41	Tsch2dil, Tscl2dil	Hold Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP50	Tssl2sch, Tssl2scl	SSx ↓ to SCKx ↑ or SCKx Input	175	—	—	ns	—
SP51	Tssh2doZ	SSx ↑ to SDOx Output High-Impedance ⁽³⁾	5	—	25	ns	—
SP52	Tsch2ssh, Tscl2ssh	SSx after SCKx Edge	Tsck + 20	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

Note 2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

Note 3: The minimum clock period for SCKx is 40 ns.

Note 4: Assumes 50 pF load on all SPIx pins.

FIGURE 29-20: PARALLEL SLAVE PORT TIMING

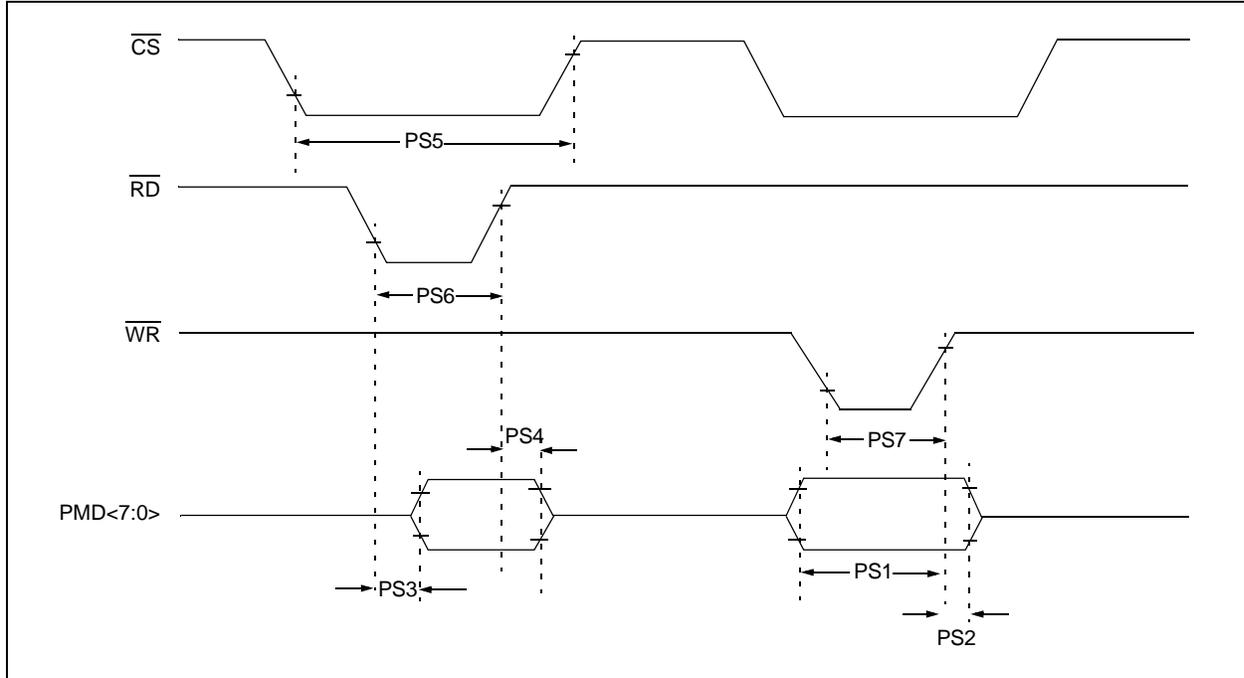


TABLE 29-37: PARALLEL SLAVE PORT REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-Temp				
Param. No.	Symbol	Characteristics ⁽¹⁾	Min.	Typical	Max.	Units	Conditions
PS1	TdtV2wrH	Data In Valid before \overline{WR} or \overline{CS} Inactive (setup time)	20	—	—	ns	—
PS2	TwrH2dtl	\overline{WR} or \overline{CS} Inactive to Data – In Invalid (hold time)	40	—	—	ns	—
PS3	TrdL2dtV	\overline{RD} and \overline{CS} Active to Data – Out Valid	—	—	60	ns	—
PS4	TrdH2dtl	\overline{RD} Active or \overline{CS} Inactive to Data – Out Invalid	0	—	10	ns	—
PS5	Tcs	\overline{CS} Active Time	$T_{PB} + 40$	—	—	ns	—
PS6	TWR	\overline{WR} Active Time	$T_{PB} + 25$	—	—	ns	—
PS7	TRD	\overline{RD} Active Time	$T_{PB} + 25$	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.